

## STWA50N65DM2AG

# Automotive-grade N-channel 650 V, 0.070 $\Omega$ typ., 38 A Power MOSFET MDmesh<sup>TM</sup> DM2 in TO-247 long leads package

Datasheet - production data

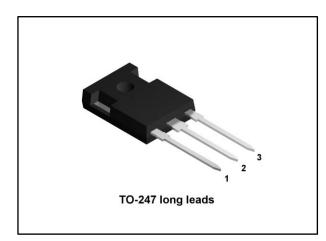
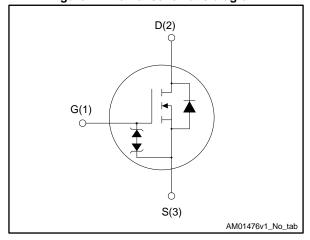


Figure 1: Internal schematic diagram



#### **Features**

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>	P <sub>TOT</sub>
STWA50N65DM2AG	650 V	0.087 Ω	38 A	300 W



- AEC-Q101 qualified
- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

### **Applications**

Switching applications

## **Description**

This high voltage N-channel Power MOSFET is part of the MDmesh  $^{\text{TM}}$  DM2 fast recovery diode series. It offers very low recovery charge (Qrr) and time (trr) combined with low RDS(on), rendering it suitable for the most demanding high efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

**Table 1: Device summary** 

Order code	Marking	Package	Packing
STWA50N65DM2AG	50N65DM2	TO-247 long leads	Tube



The HTRB test was performed at 80%  $V_{(BR)DSS}$  in compliance with AEC-Q101 rev. C. All the other tests were performed according to rev. D.

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STWA50N65DM2AG Electrical ratings

## 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>G</sub> s	Gate-source voltage	±25	V
1_	Drain current (continuous) at T <sub>case</sub> = 25 °C	38	۸
ID	Drain current (continuous) at T <sub>case</sub> = 100 °C	24	Α
I <sub>DM</sub> <sup>(1)</sup>	Drain current (pulsed)	110	Α
P <sub>TOT</sub>	Total dissipation at T <sub>case</sub> = 25 °C	300	W
dv/dt <sup>(2)</sup>	Peak diode recovery voltage slope	50	V/ns
dv/dt <sup>(3)</sup>	MOSFET dv/dt ruggedness	50	V/IIS
T <sub>stg</sub>	Storage temperature range	-55 to 150	°C
Tj	Operating junction temperature range	-55 (0 150	C

#### Notes:

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case	0.42	0000
R <sub>thj-amb</sub>			°C/W

**Table 4: Avalanche characteristics** 

Symbol	Parameter	Value	Unit
I <sub>AR</sub>	Avalanche current, repetitive or not repetitive	5	Α
E <sub>AS</sub> <sup>(1)</sup>	Single pulse avalanche energy	850	mJ

#### Notes:

 $<sup>^{\</sup>left( 1\right) }$  Pulse width is limited by safe operating area.

 $<sup>^{(2)}</sup>$   $I_{SD} \leq 38$  A, di/dt=800 A/µs;  $V_{DS}$  peak <  $V_{(BR)DSS},~V_{DD}$  = 80%  $V_{(BR)DSS}.$ 

 $<sup>^{(3)}</sup>$  V<sub>DS</sub>  $\leq$  520 V.

 $<sup>^{(1)}</sup>$  starting  $T_{j}$  = 25 °C,  $I_{D}$  =  $I_{AR},\,V_{DD}$  = 50 V.

## 2 Electrical characteristics

(T<sub>case</sub> = 25 °C unless otherwise specified)

Table 5: Static

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA	650			٧
	Zoro goto voltago droin	$V_{GS} = 0 \text{ V}, V_{DS} = 650 \text{ V}$			10	
IDSS	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 650 \text{ V},$ $T_{case} = 125 ^{\circ}\text{C}^{(1)}$			100	μA
Igss	Gate-body leakage current	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±25 V			±5	μΑ
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	3	4	5	V
R <sub>DS(on)</sub>	Static drain-source on-resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 19 A		0.070	0.087	Ω

#### Notes:

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Ciss	Input capacitance		-	3200	ı	
Coss	Output capacitance	V <sub>DS</sub> = 100 V, f = 1 MHz,	-	130	ı	pF
C <sub>rss</sub>	Reverse transfer capacitance	$V_{GS} = 0 V$	-	3	ı	ρı
Coss eq. (1)	Equivalent output capacitance	V <sub>DS</sub> = 0 to 520 V, V <sub>GS</sub> = 0 V	1	256	ı	pF
R <sub>G</sub>	Intrinsic gate resistance	f = 1 MHz, I <sub>D</sub> = 0 A	-	4	ı	Ω
$Q_g$	Total gate charge	$V_{DD} = 520 \text{ V}, I_D = 38 \text{ A},$	-	69	-	
Qgs	Gate-source charge	V <sub>GS</sub> = 0 to 10 V (see <i>Figure 15: "Test circuit for</i>	-	18	-	nC
$Q_{gd}$	Gate-drain charge	gate charge behavior")	-	34	-	

#### Notes:

<sup>&</sup>lt;sup>(1)</sup>Defined by design, not subject to production test

 $<sup>^{(1)}</sup>$   $C_{oss\ eq.}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

#### Table 7: Switching times

	<u> </u>					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 325 V, I <sub>D</sub> = 19 A	ı	22.5	1	
tr	Rise time	$R_G = 4.7 \Omega$ , $V_{GS} = 10 V$ (see Figure 14: "Test circuit for	ı	21	ı	
t <sub>d(off)</sub>	Turn-off delay time	resistive load switching times"	-	89	-	ns
t <sub>f</sub>	Fall time	and Figure 19: "Switching time waveform")	-	10.5	-	

#### Table 8: Source-drain diode

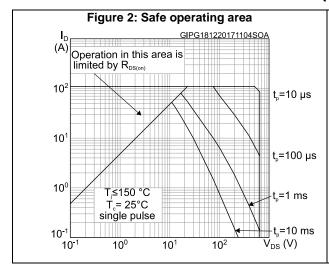
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub>	Source-drain current		-		38	Α
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		-		110	Α
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 38 A	-		1.6	V
t <sub>rr</sub>	Reverse recovery time	I <sub>SD</sub> = 38 A, di/dt = 100 A/μs,	-	150		ns
Qrr	Reverse recovery charge	$V_{DD} = 60 \text{ V}$ (see Figure 16: "Test circuit for	-	0.96		μC
I <sub>RRM</sub>	Reverse recovery current	inductive load switching and diode recovery times")	-	12.8		Α
t <sub>rr</sub>	Reverse recovery time	I <sub>SD</sub> = 38 A, di/dt = 100 A/μs,	-	245		ns
Q <sub>rr</sub>	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 \text{ °C}$ (see Figure 16: "Test circuit for	-	2.7		μC
I <sub>RRM</sub>	Reverse recovery current	inductive load switching and diode recovery times")	-	22		Α

#### Notes:

 $<sup>^{\</sup>left( 1\right) }$  Pulse width is limited by safe operating area.

 $<sup>^{(2)}</sup>$  Pulse test: pulse duration = 300  $\mu s,$  duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)



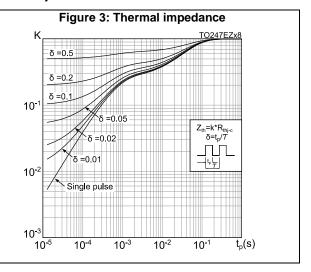


Figure 4: Output characteristics

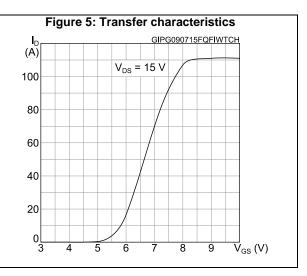
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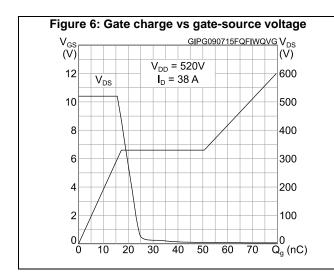
VGS = 9,10 V

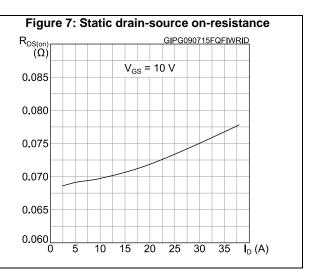
VGS = 8 V

VGS = 7 V

VGS = 6 V







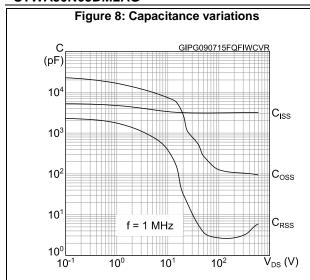
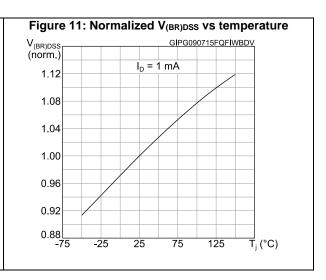
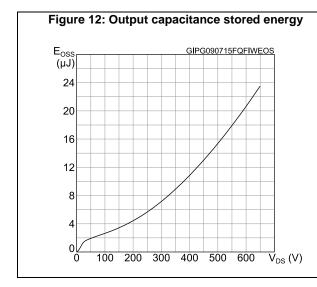
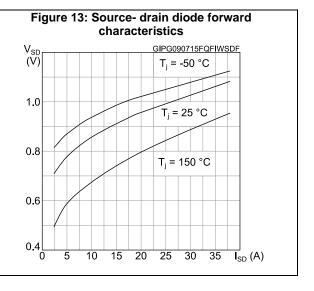


Figure 9: Normalized gate threshold voltage vs temperature V<sub>GS(th)</sub> (norm.) GIPG090715FQFIWVTH  $I_D = 250 \, \mu A$ 1.1 1.0 0.9 0.8 0.7 0.6L -75 25 75 125 T<sub>i</sub> (°C) -25

Figure 10: Normalized on-resistance vs temperature  $R_{DS(on)}$  (norm.)  $V_{GS} = 10 \text{ V}$   $V_{GS} = 10 \text{ V}$  1.8 1.4 1.0 0.6 0.2 -75 -25 25 75 125  $T_{j}$  (°C)

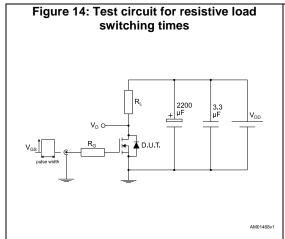


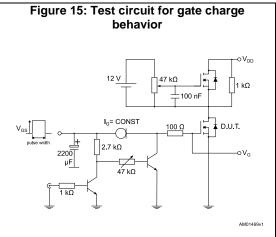


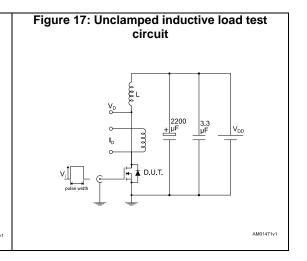


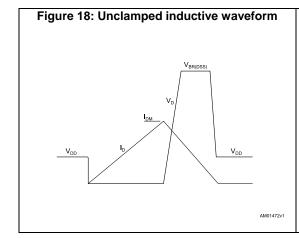
Test circuits STWA50N65DM2AG

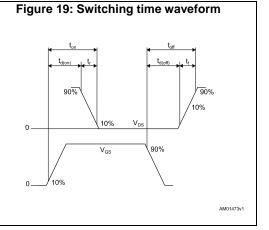
## 3 Test circuits











## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

## 4.1 TO-247 long leads package information

HEAT-SINK PLANE øΡ E3 A2-Ď A1. *b2* (3x) b 8463846\_2\_F

Figure 20: TO-247 long leads package outline

Table 9: TO-247 long leads package mechanical data

Dim	3	mm	
Dim.	Min.	Тур.	Max.
А	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
С	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
е	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
Р	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

STWA50N65DM2AG Revision history

# 5 Revision history

Table 10: Document revision history

Date	Revision	Changes
10-Jan-2017	1	Initial release
18-Dec-2017	2	Datasheet promoted from preliminary data to production data.  Modified Table 2: "Absolute maximum ratings", Table 4: "Avalanche characteristics", Table 6: "Dynamic" and Table 8: "Source-drain diode".  Modified Figure 2: "Safe operating area".  Minor text changes.

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